

Docket No. 0010-1098-0

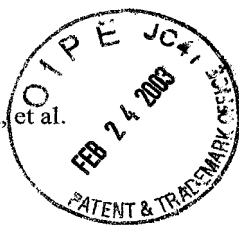
IN RE APPLICATION OF: Yasuaki SEKI, et al.

SERIAL NO: 09/539,864

FILED: March 31, 2000

CPA FILED: September 9, 2002

FOR: INSULATING RESIN COMPOSITION FOR MULTILAYER PRINTED-WIRING BOARD



ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an **Amendment and Request for Reconsideration (w/attached Marked-Up Copy)** in the above-identified application.

☐ No additional fee is required

☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.

☒ Additional documents filed herewith: Request for Extension of Time (2 months); Letter to Official Draftsman; Formal Drawings for Figures 1A-1F and 2A-2E (2 pages); Exhibit A, Webster's Third New International Dictionary, p. 464

The Fee has been calculated as shown below:

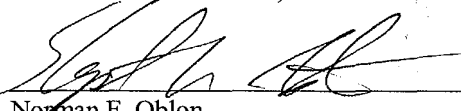
| CLAIMS      | CLAIMS<br>REMAINING |  | HIGHEST<br>NUMBER<br>PREVIOUSLY<br>PAID | NO.<br>EXTRA<br>CLAIMS | RATE      | CALCULATIONS |
|-------------|---------------------|--|---|------------------------|-----------|--------------|
| TOTAL       | 15                  | MINUS  | 20                                      | 0                      | x \$18 =  | \$0.00       |
| INDEPENDENT | 2                   | MINUS  | 3                                       | 0                      | x \$84 =  | \$0.00       |
|             |                     | <input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS                   |   |                        | + \$280 = | \$0.00       |
|             |                     | TOTAL OF ABOVE CALCULATIONS  |   |                        |           | \$0.00       |
|             |                     | <input type="checkbox"/> Reduction by 50% for filing by Small Entity |   |                        |           | \$0.00       |
|             |                     | <input type="checkbox"/> Recordation of Assignment                   |   |                        | + \$40 =  | \$0.00       |
|             |                     | TOTAL  |   |                        |           | \$0.00       |

☒ A check in the amount of **\$410.00** is attached.

☒ Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

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0010-1098-0



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

YASUAKI SEKI ET AL

: EXAMINER: PATEL

SERIAL NO.: 09/539,864

:

FILED: MARCH 31, 2000

: GROUP ART UNIT: 2827

CPA FILED: SEPTEMBER 9, 2002

FOR: INSULATING RESIN COMPOSITION  
FOR MULTILAYER PRINTED-  
WIRING BOARD

AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

In response to the Official Action dated October 3, 2002, Applicants respectfully request reconsideration of the above-identified application in view of the following amendments and remarks.

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IN THE CLAIMS

Please cancel Claim 20, without prejudice toward the further prosecution of this claim in a Continuation and/or Divisional application.

Please amend the claims as shown on the attached marked-up copy to read as follows:

22. (Amended) The multilayer printed-wiring board of Claim 21, wherein said polyamide resin has a plasma etching rate which is higher than the plasma etching rate of said